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Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

Product Status	Active
Core Processor	8051
Core Size	8-Bit
Speed	25MHz
Connectivity	SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, Temp Sensor, WDT
Number of I/O	16
Program Memory Size	8KB (8K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5.25V
Data Converters	A/D 16x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	20-VFQFN Exposed Pad
Supplier Device Package	20-QFN (4x4)
Purchase URL	https://www.e-xfl.com/product-detail/silicon-labs/c8051f531-c-im

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

SFR Definition 19.2. PCA0MD: PCA Mode	207
SFR Definition 19.3. PCA0CPMn: PCA Capture/Compare Mode	208
SFR Definition 19.4. PCA0L: PCA Counter/Timer Low Byte	209
SFR Definition 19.5. PCA0H: PCA Counter/Timer High Byte	209
SFR Definition 19.6. PCA0CPLn: PCA Capture Module Low Byte	209
SFR Definition 19.7. PCA0CPHn: PCA Capture Module High Byte	209
C2 Register Definition 21.1. C2ADD: C2 Address	214
C2 Register Definition 21.2. DEVICEID: C2 Device ID	214
C2 Register Definition 21.3. REVID: C2 Revision ID	215
C2 Register Definition 21.4. FPCTL: C2 Flash Programming Control	215
C2 Register Definition 21.5. FPDAT: C2 Flash Programming Data	215



includes software with a developer's studio and debugger, a USB debug adapter, a target application board with the associated MCU installed, and the required cables and wall-mount power supply. The development kit requires a computer with Windows installed. As shown in Figure 1.5, the PC is connected to the USB debug adapter. A six-inch ribbon cable connects the USB debug adapter to the user's application board, picking up the two C2 pins and GND.

The Silicon Laboratories IDE interface is a vastly superior developing and debugging configuration, compared to standard MCU emulators that use on-board "ICE Chips" and require the MCU in the application board to be socketed. Silicon Laboratories' debug paradigm increases ease of use and preserves the performance of the precision analog peripherals.



Figure 1.5. Development/In-System Debug Diagram



Name	Pin Numbers		Pin Numbers		Туре	Description
	'F52xA 'F52x-C	'F52x				
P0.3/TX*/	—	8	D I/O or A In	Port 0.3. See Port I/O Section for a complete description.		
XTAL2			D I/O	External Clock Output. For an external crystal or resonator, this pin is the excitation driver. This pin is the external clock input for CMOS, capacitor, or RC oscillator configurations. See Section "14. Oscillators" on page 135.		
P0.2	9	9	D I/O or	Port 0.2. See Port I/O Section for a complete description.		
XTAL1			A In	External Clock Input. This pin is the external oscillator return for a crystal or resonator. Section "14. Oscillators" on page 135.		
P0.1/	10	10	D I/O or A In	Port 0.1. See Port I/O Section for a complete description.		
C2D			D I/O	Bi-directional data signal for the C2 Debug Interface		
Note: Please	refer to Se	ection "2	20. Device S	Specific Behavior" on page 210.		

Table 3.1. Pin Definitions for the C8051F52x and C8051F52xA (DFN 10) (Continued)





Figure 3.5. TSSOP-20 Package Diagram

Symbol	Min	Nom	Max
А		_	1.20
A1	0.05	_	0.15
A2	0.80	1.00	1.05
b	0.19		0.30
С	0.09		0.20
D	6.40	6.50	6.60
е		0.65 BSC.	ľ
E		6.40 BSC.	
E1	4.30	4.40	4.50
L	0.45	0.60	0.75
θ1	0°		8°
aaa		0.10	-1
bbb		0.10	
ddd		0.20	
Notes:			

Table 3.5. TSSOP-20 Package Diagram Dimensions

1. All dimensions shown are in millimeters (mm).

2. Dimensioning and Tolerancing per ANSI Y14.5M-1994.

3. This drawing conforms to JEDEC outline MO-153, variation AC.

4. Recommended card reflow profile is per the JEDEC/IPC J-STD-020 specification for Small Body Components.



4. 12-Bit ADC (ADC0)

The ADC0 on the C8051F52x/F52x/F53x/F53x/F53xA Family consists of an analog multiplexer (AMUX0) with 16/6 total input selections, and a 200 ksps, 12-bit successive-approximation-register (SAR) ADC with integrated track-and-hold, programmable window detector, programmable gain, and hardware accumulator. The ADC0 subsystem has a special Burst Mode which can automatically enable ADC0, capture and accumulate samples, then place ADC0 in a low power shutdown mode without CPU intervention. The AMUX0, data conversion modes, and window detector are all configurable under software control via the Special Function Registers shown in Figure 4.1. ADC0 inputs are single-ended and may be configured to measure P0.0-P1.7, the Temperature Sensor output, V_{DD} , or GND with respect to GND. The voltage reference for the ADC is selected as described in Section "5. Voltage Reference" on page 72. ADC0 is enabled when the AD0EN bit in the ADC0 Control register (ADC0CN) is set to logic 1, or when performing conversions in Burst Mode. ADC0 is in low power shutdown when AD0EN is logic 0 and no Burst Mode conversions are taking place.



Figure 4.1. ADC0 Functional Block Diagram

4.1. Analog Multiplexer

AMUX0 selects the input channel to the ADC. Any of the following may be selected as an input: P0.0–P1.7, the on-chip temperature sensor, the core power supply (V_{DD}), or ground (GND). **ADC0 is single-ended and all signals measured are with respect to GND.** The ADC0 input channels are selected using the ADC0MX register as described in SFR Definition 4.4.

Important Note About ADC0 Input Configuration: Port pins selected as ADC0 inputs should be configured as analog inputs, and should be skipped by the Digital Crossbar. To configure a Port pin for analog input, set to 0 the corresponding bit in register PnMDIN (for n = 0,1). To force the Crossbar to skip a Port pin, set to 1 the corresponding bit in register PnSKIP (for n = 0,1). See Section "13. Port Input/Output" on page 120 for more Port I/O configuration details.



For example, the initial example in this section requires a gain of 0.44 to convert 5 V full scale to 2.2 V full scale. Using Equation 4.3:

$$GAIN = \left(0.44 - GAINADD \times \left(\frac{1}{64}\right)\right) \times 4096$$

If GAINADD is set to 1, this makes the equation:

$$GAIN = \left(0.44 - 1 \times \left(\frac{1}{64}\right)\right) \times 4096 = 0.424 \times 4096 = 1738 = 0x06CA$$

The actual gain from setting GAINADD to 1 and ADC0GNH and ADC0GNL to 0x6CA is 0.4399. A similar gain can be achieved if GAINADD is set to 0 with a different value for ADC0GNH and ADC0GNL.

4.4.2. Setting the Gain Value

The three programmable gain registers are accessed indirectly using the ADC0H and ADC0L registers when the GAINEN bit (ADC0CF.0) bit is set. ADC0H acts as the address register, and ADC0L is the data register. The programmable gain registers can only be written to and cannot be read. See Gain Register Definition 4.1, Gain Register Definition 4.2, and Gain Register Definition 4.3 for more information.

The gain is programmed using the following steps:

- 1. Set the GAINEN bit (ADC0CF.0)
- 2. Load the ADC0H with the ADC0GNH, ADC0GNL, or ADC0GNA address.
- 3. Load ADC0L with the desired value for the selected gain register.
- 4. Reset the GAINEN bit (ADC0CF.0)

Notes:

- 1. An ADC conversion should not be performed while the GAINEN bit is set.
- 2. Even with gain enabled, the maximum input voltage must be less than V_{REGIN} and the maximum voltage of the signal after gain must be less than or equal to V_{REF}.

In code, changing the value to 0.44 gain from the previous example looks like:

```
// in 'C':

ADC0CF |= 0x01;// GAINEN = 1

ADC0H = 0x04;// Load the ADC0GNH address

ADC0L = 0x6C;// Load the upper byte of 0x6CA to ADC0GNH

ADC0H = 0x07;// Load the ADC0GNL address

ADC0L = 0xA0;// Load the lower nibble of 0x6CA to ADC0GNL

ADC0H = 0x08;// Load the ADC0GNA address

ADC0L = 0x01;// Set the GAINADD bit

ADC0CF &= ~0x01;// GAINEN = 0
```

; in assembly ORL ADC0CF,#01H ; GAINEN = 1 MOV ADC0H,#04H; Load the ADC0GNH address MOV ADC0L,#06CH ; Load the upper byte of 0x6CA to ADC0GNH MOV ADC0H,#07H; Load the ADC0GNL address MOV ADC0L,#0A0H ; Load the lower nibble of 0x6CA to ADC0GNL MOV ADC0L,#0A0H ; Load the ADC0GNA address MOV ADC0H,#08H; Load the ADC0GNA address MOV ADC0L,#01H ; Set the GAINADD bit ANL ADC0CF,#0FEH ; GAINEN = 0



4.5. Programmable Window Detector

The ADC Programmable Window Detector continuously compares the ADC0 output registers to user-programmed limits, and notifies the system when a desired condition is detected. This is especially effective in an interrupt-driven system, saving code space and CPU bandwidth while delivering faster system response times. The window detector interrupt flag (AD0WINT in register ADC0CN) can also be used in polled mode. The ADC0 Greater-Than (ADC0GTH, ADC0GTL) and Less-Than (ADC0LTH, ADC0LTL) registers hold the comparison values. The window detector flag can be programmed to indicate when measured data is inside or outside of the user-programmed limits, depending on the contents of the ADC0 Less-Than and ADC0 Greater-Than registers.

SFR Definition 4.10. ADC0GTH: ADC0 Greater-Than Data High Byte



SFR Definition 4.11. ADC0GTL: ADC0 Greater-Than Data Low Byte





SFR Definition 4.12. ADC0LTH: ADC0 Less-Than Data High Byte



SFR Definition 4.13. ADC0LTL: ADC0 Less-Than Data Low Byte





Table 8.1. CIP-51 Instruction Set Summary (Continued)

Mnemonic	Description	Bytes	Clock Cycles
ORL direct, #data	OR immediate to direct byte	3	3
XRL A, Rn	Exclusive-OR Register to A	1	1
XRL A, direct	Exclusive-OR direct byte to A	2	2
XRL A, @Ri	Exclusive-OR indirect RAM to A	1	2
XRL A, #data	Exclusive-OR immediate to A	2	2
XRL direct, A	Exclusive-OR A to direct byte	2	2
XRL direct, #data	Exclusive-OR immediate to direct byte	3	3
CLR A	Clear A	1	1
CPL A	Complement A	1	2
RL A	Rotate A left	1	1
RLC A	Rotate A left through Carry	1	1
RR A	Rotate A right	1	1
RRC A	Rotate A right through Carry	1	1
SWAP A	Swap nibbles of A	1	1
Data Transfer			
MOV A, Rn	Move Register to A	1	1
MOV A, direct	Move direct byte to A	2	2
MOV A, @Ri	Move indirect RAM to A	1	2
MOV A, #data	Move immediate to A	2	2
MOV Rn, A	Move A to Register	1	1
MOV Rn, direct	Move direct byte to Register	2	2
MOV Rn, #data	Move immediate to Register	2	2
MOV direct, A	Move A to direct byte	2	2
MOV direct, Rn	Move Register to direct byte	2	2
MOV direct, direct	Move direct byte to direct byte	3	3
MOV direct, @Ri	Move indirect RAM to direct byte	2	2
MOV direct, #data	Move immediate to direct byte	3	3
MOV @Ri, A	Move A to indirect RAM	1	2
MOV @Ri, direct	Move direct byte to indirect RAM	2	2
MOV @Ri, #data	Move immediate to indirect RAM	2	2
MOV DPTR, #data16	Load DPTR with 16-bit constant	3	3
MOVC A, @A+DPTR	Move code byte relative DPTR to A	1	3
MOVC A, @A+PC	Move code byte relative PC to A	1	3
MOVX A, @Ri	Move external data (8-bit address) to A	1	3
MOVX @Ri, A	Move A to external data (8-bit address)	1	3
MOVX A, @DPTR	Move external data (16-bit address) to A	1	3
MOVX @DPTR, A	Move A to external data (16-bit address)	1	3
PUSH direct	Push direct byte onto stack	2	2
POP direct	Pop direct byte from stack	2	2
XCH A, Rn	Exchange Register with A	1	1
XCH A, direct	Exchange direct byte with A	2	2
XCH A, @Ri	Exchange indirect RAM with A	1	2
XCHD A, @Ri	Exchange low nibble of indirect RAM with A	1	2



SFR Definition 10.2. IP: Interrupt Priority R/W R/W R/W R/W R/W R/W Reset Value R R/W PT2 PS0 -PSPI0 PT1 PX1 PT0 PX0 10000000 Bit Bit7 Bit6 Bit5 Bit4 Bit3 Bit2 Bit1 Bit0 Addressable SFR Address: 0xB8 Bit7: **UNUSED**. Read = 1b: Write = don't care. Bit6: PSPI0: Serial Peripheral Interface (SPI0) Interrupt Priority Control. This bit sets the priority of the SPI0 interrupt. 0: SPI0 interrupt set to low priority level. 1: SPI0 interrupt set to high priority level. Bit5: PT2: Timer 2 Interrupt Priority Control. This bit sets the priority of the Timer 2 interrupt. 0: Timer 2 interrupt set to low priority level. 1: Timer 2 interrupt set to high priority level. Bit4: **PS0**: UARTO Interrupt Priority Control. This bit sets the priority of the UART0 interrupt. 0: UART0 interrupt set to low priority level. 1: UART0 interrupt set to high priority level. Bit3: PT1: Timer 1 Interrupt Priority Control. This bit sets the priority of the Timer 1 interrupt. 0: Timer 1 interrupt set to low priority level. 1: Timer 1 interrupt set to high priority level. Bit2: **PX1**: External Interrupt 0 Priority Control. This bit sets the priority of the external interrupt 1. 0: INT1 interrupt set to low priority level. 1: INT1 interrupt set to high priority level. PT0: Timer 0 Interrupt Priority Control. Bit1: This bit sets the priority of the Timer 0 interrupt. 0: Timer 0 interrupt set to low priority level. 1: Timer 0 interrupt set to high priority level. Bit0: **PX0**: External Interrupt 0 Priority Control. This bit sets the priority of the external interrupt 0. 0: INT0 interrupt set to low priority level. 1: INT0 interrupt set to high priority level.



12.2. Flash Write and Erase Guidelines

Any system which contains routines which write or erase Flash memory from software involves some risk that the write or erase routines will execute unintentionally if the CPU is operating outside its specified operating range of V_{DD} , system clock frequency, or temperature. This accidental execution of Flash modi-fying code can result in alteration of Flash memory contents causing a system failure that is only recoverable by re-Flashing the code in the device.

The following guidelines are recommended for any system which contains routines which write or erase Flash from code.

12.2.1. V_{DD} Maintenance and the V_{DD} monitor

- 1. If the system power supply is subject to voltage or current "spikes," add sufficient transient protection devices to the power supply to ensure that the supply voltages listed in the Absolute Maximum Ratings table are not exceeded.
- Make certain that the maximum V_{DD} ramp time specification (if applicable) is met. See Section 20.4 on page 211 for more details on V_{DD} ramp time. If th<u>e sy</u>stem cannot meet this ramp time specification, then add an external V_{DD} brownout circuit to the RST pin of th<u>e</u> device that holds the device in reset until V_{DD} reaches the minimum specified V_{DD} and re-asserts RST if V_{DD} drops belowthat level. V_{DD} (min) is specified in Table 2.2 on page 26.
- 3. Enable the on-chip V_{DD} monitor (VDDMON0) and enable it as a reset source as early in code as possible. This should be the first set of instructions executed after the Reset Vector. For C-based systems, this will involve modifying the startup code added by the C compiler. See your compiler documentation for more details. Make certain that there are no delays in software between enabling the V_{DD} monitor (VDDMON0) and enabling it as a reset source. Code examples showing this can be found in "AN201: Writing to Flash from Firmware", available from the Silicon Laboratories web site.
- 4. As an added precaution, explicitly enable the V_{DD} monitor (VDDMON0) and enable the V_{DD} monitor as a reset source inside the functions that write and erase Flash memory. The V_{DD} monitor enable instructions should be placed just after the instruction to set PSWE to a 1, but before the Flash write or erase operation instruction.
- Make certain that all writes to the RSTSRC (Reset Sources) register use direct assignment operators and explicitly DO NOT use the bit-wise operators (such as AND or OR). For example, "RSTSRC = 0x02" is correct. "RSTSRC |= 0x02" is incorrect.
- 6. Make certain that all writes to the RSTSRC register explicitly set the PORSF bit to a 1. Areas to check are initialization code which enables other reset sources, such as the Missing Clock Detector or Comparator, for example, and instructions which force a Software Reset. A global search on "RSTSRC" can quickly verify this.

12.2.2. PSWE Maintenance

- 1. Reduce the number of places in code where the PSWE bit (PSCTL.0) is set to a 1. There should be exactly one routine in code that sets PSWE to a 1 to write Flash bytes and one routine in code that sets PSWE and PSEE both to a 1 to erase Flash pages.
- Minimize the number of variable accesses while PSWE is set to a 1. Handle pointer address updates and loop variable maintenance outside the "PSWE = 1;... PSWE = 0;" area. Code examples showing this can be found in "AN201: Writing to Flash from Firmware," available from the Silicon Laboratories web site.
- 3. Disable interrupts prior to setting PSWE to a 1 and leave them disabled until after PSWE has been reset to '0'. Any interrupts posted during the Flash write or erase operation will be serviced in priority order after the Flash operation has been completed and interrupts have been re-enabled by software.
- Make certain that the Flash write and erase pointer variables are not located in XRAM. See your compiler documentation for instructions regarding how to explicitly locate variables in different memory areas.



5. Add address bounds checking to the routines that write or erase Flash memory to ensure that a routine called with an illegal address does not result in modification of the Flash.

12.2.3. System Clock

- 1. If operating from an external crystal, be advised that crystal performance is susceptible to electrical interference and is sensitive to layout and to changes in temperature. If the system is operating in an electrically noisy environment, use the internal oscillator or use an external CMOS clock.
- 2. If operating from the external oscillator, switch to the internal oscillator during Flash write or erase operations. The external oscillator can continue to run, and the CPU can switch back to the external oscillator after the Flash operation has completed.

Additional Flash recommendations and example code can be found in application note "AN201: Writing to Flash from Firmware," available from the Silicon Laboratories website.



SFR Definition 13.7. P0MAT: Port0 Match



SFR Definition 13.8. P0MASK: Port0 Mask





SFR Definition 14.1. OSCICN: Internal Oscillator Control

R/W	R/W	R/W	R	R	R/W	R/W	R/W	Reset Value
IOSCEN	1 IOSCEN0	SUSPEND	IFRDY	_	IFCN2	IFCN1	IFCN0	11000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	-
							SFR Address	0xB2
Bits7–6:	IOSCEN[1:0)]: Internal O	scillator Er	nable Bits.				
	00: Oscillato	r Disabled.						
	01: Reserve	d.						
	10. Reserve	u. r Enablad in	Normal M	odo and Dir	sobled in Si	ucpond Mo	do	
Bit5 [.]	SUSPEND	Internal Osci	Ilator Susr	end Enable	sableu in S	uspenu mu	ue.	
Bito.	Setting this b	bit to logic 1	places the	internal os	cillator in S	USPEND n	node. The ir	nternal oscil-
	lator resume	es operation	when one	of the SUSI	PEND mod	e awakenir	ng events og	cur.
Bit4:	IFRDY: Inter	nal Oscillato	r Frequenc	cy Ready F	lag.		0	
	0: Internal O	scillator is no	ot running	at program	med freque	ency.		
	1: Internal O	scillator is ru	inning at p	rogrammed	I frequency			
Bit3:	UNUSED. R	ead = 0b, W	rite = don't	care.				
Bits2–0:	IFCN2–0: In	ternal Oscilla	ator Freque	ency Contro	ol Bits.			
	000: SYSCL	K derived fro	om Internal	Oscillator	divided by	128 (defau	lt).	
		K derived fro	om Internal	Oscillator	divided by (64. 22		
	010. 51501	K derived fro	m Internal	Oscillator	divided by a	32. 16		
	100: SYSCI	K derived fro	om Internal	Oscillator	divided by	8		
	101: SYSCL	K derived fro	om Internal	l Oscillator	divided by 4	4.		
	110: SYSCL	K derived fro	m Internal	Oscillator	divided by 2	2.		
	111: SYSCL	K derived fro	m Internal	Oscillator of	divided by 1	1.		



SFR Definition 14.4. OSCXCN: External Oscillator Control

R	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value				
XTLVLD	XOSCMD2	XOSCMD1	XOSCMD0	Reserved	XFCN2	XFCN1	XFCN0	00000000				
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0					
							SFR Address	s: 0xB1				
Di+7		wetal Ocaill	ator Valid Ek	na (Pondio			- 11v)					
DILT.	0 [·] Crystal O	scillator is u	inused or no	ay. (Reau o of vet stable	my when /		= 11X.)					
	1: Crystal O	scillator is r	unning and s	stable.								
Bits6-4:	XOSCMD2-0: External Oscillator Mode Bits.											
	00x: External Oscillator circuit off.											
	010: Externa	al CMOS CI	ock Mode.	المالين الم	· O atama							
	100 RC Os	al CIVIOS CI cillator Mod	ock wode w	ith divide by	/ 2 stage.							
	100: 100 OS	tor Oscillato	or Mode.									
	110: Crystal	Oscillator N	/lode.									
	111: Crystal	Oscillator N	lode with div	vide by 2 st	age.							
Bit3:	RESERVED	\mathbf{R} . Read = 0	o; Must write	e Ob.								
BItS2-U	000-111: Se	e table belo	w:	Jency Conti	OI BITS.							
	XECN	Crystal ()	(OSCMD = '	11x) RC	XOSCMD	(= 10x)	C (XOSCI	MD = 10x				
	000	f c			f < 25 kL	- 100,	K Easta	r = 0.97				
	000	20 kH-		- 25				r = 0.67				
	010		$< 1 \ge 30$ Km	2 20	$K \square Z < I \ge ($			r = 2.0				
	010			12 50	$\frac{\nabla \nabla \mathcal{L}}{\nabla \mathcal{L}} = \frac{\nabla \mathcal{L}}{\nabla \mathcal{L}}$			r = 7.7				
	100		$<1 \ge 413$ Kr	12 100 $1_7 200$	$\frac{K \prod Z < 1 \ge Z}{V \prod Z < f < Z}$		K Fact	DI = ZZ				
	100		< f < 3.1 Mi	12 200 Hz 400	$\frac{ \mathbf{x} ^2 < \mathbf{z} \le 1}{ \mathbf{y} ^2 < \mathbf{z} \le 1}$		K Facto	r = 180				
	110	2.1 MU-	$<$ $1 \leq 3.1$ IVII	12 400 J-7 900	$\frac{ \mathbf{r} ^2}{ \mathbf{r} ^2} < \mathbf{f} < 1$		K Facto	r = 664				
	111	3.1 MHZ	$<$ I \geq 0.2 IVII	12 000			K Factor	r = 0.04				
		0.2 1011 12		12 1.01	$\frac{1}{2} \leq 1 \leq 1$	5.2 1011 12	IN I ACIUI	- 1390				
Crystal N	lode (Circuit	from Figure	e 14.1, Optio	n 1; XOSC	MD = 11x)							
PC Mode	Choose XF(CN value to	match cryst	al or resona	ator freque	ncy.						
	Choose XF	CN value to	match frequ	iencv range	= 10x) :							
	$f = 1.23(10^3)$)/(R x C).	where									
	f = frequenc	y of clock ir	MHz									
	C = capacito	or value in p	F									
O Mada (R = Pullup r	esistor valu	e in kΩ Ontion 0. V		1 () ,)							
C Wode (-igure 14.1, actor (KE) f	Option 3; X	USCMD =	1UX) nev desire	d.						
	f = KF / (C)	מכוטו (ועד) וי ג V הם) . whe	re	allon neque		u.						
	f = frequenc	v of clock in	MHz									
	C = capacito	or value the	XTAL2 pin i	n pF								
	$V_{DD} = Powe$	er Supply on	MCU in vol	ts								



15.1. Enhanced Baud Rate Generation

The UART0 baud rate is generated by Timer 1 in 8-bit auto-reload mode. The TX clock is generated by TL1; the RX clock is generated by a copy of TL1 (shown as RX Timer in Figure 15.2), which is not useraccessible. Both TX and RX Timer overflows are divided by two to generate the TX and RX baud rates. The RX Timer runs when Timer 1 is enabled, and uses the same reload value (TH1). However, an RX Timer reload is forced when a START condition is detected on the RX pin. This allows a receive to begin any time a START is detected, independent of the TX Timer state.



Figure 15.2. UART0 Baud Rate Logic

Timer 1 should be configured for Mode 2, 8-bit auto-reload (see Section "18.1.3. Mode 2: 8-bit Counter/Timer with Auto-Reload" on page 184). The Timer 1 reload value should be set so that overflows will occur at two times the desired UART baud rate frequency. Note that Timer 1 may be clocked by one of six sources: SYSCLK, SYSCLK / 4, SYSCLK / 12, SYSCLK / 48, the external oscillator clock / 8, or an external input T1. The UART0 baud rate is determined by Equation 15.1-A and Equation 15.1-B.

A) UartBaudRate =
$$\frac{1}{2} \times T1_Overflow_Rate$$

B) T1_Overflow_Rate = $\frac{T1_{CLK}}{256 - TH1}$

Equation 15.1. UART0 Baud Rate

Where $T1_{CLK}$ is the frequency of the clock supplied to Timer 1, and T1H is the high byte of Timer 1 (8-bit auto-reload mode reload value). Timer 1 clock frequency is selected as described in Section "18. Timers" on page 182. A quick reference for typical baud rates and system clock frequencies is given in Table 15.1. Note that the internal oscillator may still generate the system clock when the external oscillator is driving Timer 1.



The shift register contents are locked after the slave detects the first edge of SCK. Writes to SPI0DAT that occur after the first SCK edge will be held in the TX latch until the end of the current transfer.

When configured as a slave, SPI0 can be configured for 4-wire or 3-wire operation. The default, 4-wire slave mode, is active when NSSMD1 (SPI0CN.3) = 0 and NSSMD0 (SPI0CN.2) = 1. In 4-wire mode, the NSS signal is routed to a port pin and configured as a digital input. SPI0 is enabled when NSS is logic 0, and disabled when NSS is logic 1. The bit counter is reset on a falling edge of NSS. Note that the NSS signal must be driven low at least 2 system clocks before the first active edge of SCK for each byte transfer. Figure 16.4 shows a connection diagram between two slave devices in 4-wire slave mode and a master device.

3-wire slave mode is active when NSSMD1 (SPI0CN.3) = 0 and NSSMD0 (SPI0CN.2) = 0. NSS is not used in this mode, and is not mapped to an external port pin through the crossbar. Since there is not a way of uniquely addressing the device in 3-wire slave mode, SPI0 must be the only slave device present on the bus. It is important to note that in 3-wire slave mode there is no external means of resetting the bit counter that determines when a full byte has been received. The bit counter can only be reset by disabling and re-enabling SPI0 with the SPIEN bit. Figure 16.3 shows a connection diagram between a slave device in 3-wire slave mode and a master device.

16.4. SPI0 Interrupt Sources

When SPI0 interrupts are enabled, the following four flags will generate an interrupt when they are set to logic 1:

Note that all of the following interrupt bits must be cleared by software.

- 1. The SPI Interrupt Flag, SPIF (SPI0CN.7) is set to logic 1 at the end of each byte transfer. This flag can occur in all SPI0 modes.
- 2. The Write Collision Flag, WCOL (SPI0CN.6) is set to logic 1 if a write to SPI0DAT is attempted when the transmit buffer has not been emptied to the SPI shift register. When this occurs, the write to SPI0DAT will be ignored, and the transmit buffer will not be written. This flag can occur in all SPI0 modes.
- 3. The Mode Fault Flag MODF (SPI0CN.5) is set to logic 1 when SPI0 is configured as a master in multimaster mode and the NSS pin is pulled low. When a Mode Fault occurs, the MSTEN and SPIEN bits in SPI0CN are set to logic 0 to disable SPI0 and allow another master device to access the bus.
- 4. The Receive Overrun Flag RXOVRN (SPI0CN.4) is set to logic 1 when configured as a slave, and a transfer is completed while the receive buffer still holds an unread byte from a previous transfer. The new byte is not transferred to the receive buffer, allowing the previously received data byte to be read. The data byte which caused the overrun is lost.



SFR Definition 17.8. LIN0DT5: LIN0 Data Byte 5



SFR Definition 17.9. LIN0DT6: LIN0 Data Byte 6



SFR Definition 17.10. LIN0DT7: LIN0 Data Byte 7



SFR Definition 17.11. LIN0DT8: LIN0 Data Byte 8





SFR Definition 17.13. LIN0ST: LIN0 STATUS Register

R	R	R	R	R/W	R	R	R	Reset Value
ACTIVE	IDLTOUT	ABORT	DTREQ	LININT	ERROR	WAKEUP	DONE	00000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	J
							Address:	0x09 (indirect)
Bit7:	ACTIVE: LIN	Bus Activi	ty Bit.					
	0: No transm	hission activ	vity detected	d on the LIN	l bus.			
	1: Transmiss	sion activity	detected of	n the LIN bu	JS.			
Bit6:	IDLTOUT: B	us Idle Time	eout Bit (sia	ave mode o	only).			
	0: The bus h	as not beel	n idle for fol	ur seconds.	مممعام امبينا	the hue is a		
Bit5.		arted transp	een delecte	a lor iour s	econas, bui	the bus is r	iot yet in Sie	sep mode.
DILJ.		nt transmis	sion has no	t heen inter	runted or st	onned This	hit is reset	to 0 after
	receiving a S	SYNCH BRI	FAK that do	es not inter	rupt a pend	ling transmis	ssion	
	1: New SYN	CH BREAK	detected b	efore the e	nd of the las	st transmissi	ion or the S	TOP bit
	(LIN0CTRL.	7) has beer	n set.					
Bit4:	DTREQ: Dat	a Request	bit (slave n	node only).				
	0: Data ident	tifier has no	t been rece	eived.				
	1: Data ident	tifier has be	en received	d.				
Bit3:	LININT: Inter	rrupt Reque	est bit.					、
	0: An interru	pt is not pe	nding. This	bit is cleare	d by setting	grstint (L	INOCTRL3)
Bi+2.	T: There is a	penaing Li	NU Interrup	ι.				
DILZ.	0. No error h	ininiunicalic las heen de	nterted Thi	s hit is clear	ed hv settir			2)
	1: An error h	as been de	tected.	5 511 15 61641	cu by Setti	IS NOTENIN		
Bit1:	WAKEUP: V	Vakeup Bit.						
	0: A wakeup	signal is no	ot being trai	nsmitted an	d has not b	een received	d.	
	1: A wakeup	signal is be	eing transm	itted or has	been recei	ved.		
Bit0:	DONE: Tran	smission C	omplete Bit					
	0: A transmis	ssion is not	in progress	or has not	been starte	d. This bit is	cleared at t	the start of
	a transmissio	on.						
	1: The curre	nt transmis	sion is com	plete.				



R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value				
TF2H	TF2L	TF2LEN	TF2CEN	T2SPLIT	TR2		T2XCLK	0000000				
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	Bit Addressable				
	Address: 0)											
Bit7:	TF2H: Time	r 2 High By	te Overflow	Flag.								
	Set by hardware when the Timer 2 high byte overflows from 0xFF to 0x00. In 16 bit mode,											
	this will occur when Timer 2 overflows from 0xFFFF to 0x0000. When the Timer 2 interrupt is enabled, setting this bit causes the CPU to vector to the Timer 2 interrupt service routine.											
	TF2H is not	automatica	llv cleared l	ov hardware	and must l	be cleared	bv software	e rouine.				
Bit6:	TF2L: Time	r 2 Low Byte	e Overflow	Flag.								
	Set by hard	ware when	the Timer 2	low byte over	erflows fror	m 0xFF to	0x00. When	this bit is				
	set, an inter	rupt will be	generated if	TF2LEN is	set and Tin	ner 2 interr	upts are ena	abled. TF2L				
	will set when	n the low by	te overflow	s regardless	of the 1im	er 2 mode	. This bit is r	not automat				
Bit5 [.]	TF2LEN. Ti	mer 2 I ow F	are. Byte Interru	ot Enable								
	This bit ena	bles/disable	es Timer 2 L	ow Byte inte	errupts. If T	F2LEN is	set and Time	er 2 inter-				
	rupts are en	abled, an ir	nterrupt will	be generate	d when the	e low byte	of Timer 2 ov	verflows.				
	This bit sho	uld be clear	ed when op	erating Time	er 2 in 16-b	oit mode.						
	0: Timer 2 L	ow Byte inte	errupts disa	bled. bled								
Rit4 [.]	TE2CEN Ti	mer 2 Cant	ure Enable	bieu.								
51(1)	0: Timer 2 c	apture mod	e disabled.									
	1: Timer 2 c	apture mod	e enabled.									
Bit3:	T2SPLIT: Ti	mer 2 Split	Mode Enab	le.								
	When this b	it is set, Tin	her 2 operat	es as two 8-	bit timers v	with auto-re	eload.					
	0: Timer 2 0 1: Timer 2 0	perates in 1	two 8-bit auto-r	eload mode.	Ders							
Bit2:	TR2: Timer	2 Run Cont	rol.		1013.							
	This bit ena	bles/disable	es Timer 2. I	n 8-bit mode	e, this bit ei	nables/disa	ables TMR2	H only;				
	TMR2L is al	lways enabl	ed in this m	ode.								
	0: Timer 2 disabled.											
Rit1.	1: Timer 2 e	nabled.	rite - don't	care								
Bit0:	T2XCLK: Ti	mer 2 Exter	nal Clock S	elect.								
	This bit sele	cts the exte	rnal clock s	ource for Tir	ner 2. If Tir	mer 2 is in	8-bit mode,	this bit				
	selects the	external osc	illator clock	source for b	ooth timer b	oytes. How	vever, the Tir	ner 2 Clock				
	Select bits (T2MH and	T2ML in reg	ister CKCO	N) may still	l be used t	o select bety	ween the				
	external clo	ck and the s	system clock	k for either ti	mer. n clock divi	ided by 12						
	1. Timer 2 e	xternal cloc	k selection	is the extern	al clock div	vided by 12	•					

